

| Moisture sensitivity level: Level 1

FEATURES

Surface Mounting Design 5.4*5.4*5.0mm

High Current Handling Capability 5000A @ 8/20 µs

Low Capacitance and Insertion Loss

Quick Response and Long Service Life



5.4*5.4*5.0mm



APPLICATION INFORMATION

Communication equipment.	
Repeaters, Modems	
Telephone Interface,Line cards.	
Data communication equipment.	

AGENCY APPROVALS

lcon	Solderability		
RoHS	Compliance with 2011/65/EU		
HF	Compliance with IEC61249-2-21;2003		
P 6	Mean lead free		
IR.	UL Certificated E505857		

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish	
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated	



ELECTRICAL PARAMETER

Parameter	Condition	Rating	
DC Spark-over Voltage 1)	100V/s	53-97	
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤650	V
impuise spaik-over voltage	At 1kV/μs	Typical values of distribution ≤600	
Discharge Current (8/20us) 2)	10 times	5	KA
AC Discharge Current	50Hz, 1S	5	
Minimum Insulation Resistance	Test Voltage DC=25V	1	
Max. Capacitance 1MHz	V _{DC} =0.5V	1	
Operating and Storage Temperature		-40~125	°C

¹⁾ In ionized mode

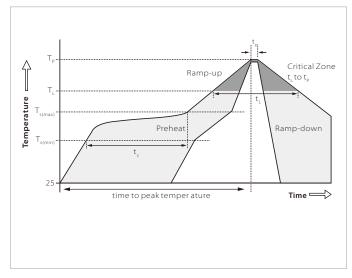
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C; Time:2H	
Low Temperature Storage Test	Temperature: -40°C ; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

REFLOW PROFILE

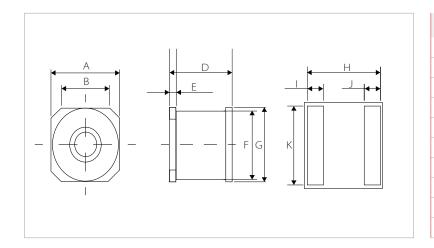
Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
Time(min to max)		60-180 secs	
Average ramp up rate (Liquidus)Temp (T_L) to peak T_s (max)to T_L - Ramp-up Rate		3°C/second max	
Reflow	Temperature (T _L) (Liquidus)	217℃	
Kellow	Temperature (T_L)	60-150 seconds	
PeakTem	perature (T,)	245~260°C	
Time within 5°C of actual peak Temperature (tp)		30 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T₅)		8 minutes max.	
Do not exceed		260°C	



²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

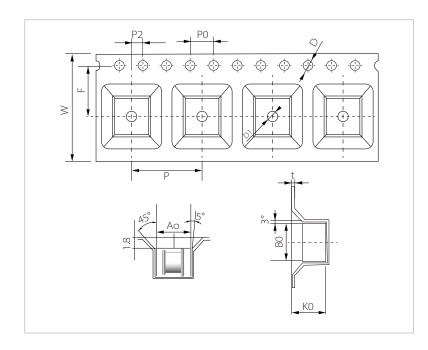


DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm		
А	5.4±0.1		
В	3.8		
D	5.0±0.2		
Е	0.5±0.1		
F	Ф5.0±0.1		
G	Ф5.4±0.1		
Н	5.7		
I	1.2		
J	1.2		
K	5.8		

PACKAGE REEL INFORMATION



Ref.	mm
W	16.0±0.3
Р	12.0±0.1
F	7.5±0.1
P2	2.0±0.1
D	1.5±0.1
D1	1.5±0.1
PO	4.0±0.1
10P0	40.0±0.2
A0	5.7±0.1
ВО	5.7±0.1
KO	5.7±0.1
t	0.4±0.05

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R05B075A	5.4*5.4*5.0mm	⅓ SG075 <u>05</u>	800	13"



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